

PATENT ASSIGNMENT

Electronic Version v08
 Stylesheet Version v02

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | |
|--|-----------------------------------|------------------|----------------|--------------------|-------------|---------------|-------------|------------------|-----------------------------|--|-------|----|----------|
| NATURE OF CONVEYANCE: | ASSIGNMENT OF ASSIGNOR'S INTEREST | | | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | | | |
| <table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kenichiro Aridome</td> <td>2005-04-22</td> </tr> <tr> <td>Osamu Date</td> <td>2005-04-22</td> </tr> </tbody> </table> | | Name | Execution Date | Kenichiro Aridome | 2005-04-22 | Osamu Date | 2005-04-22 | | | | | | |
| Name | Execution Date | | | | | | | | | | | | |
| Kenichiro Aridome | 2005-04-22 | | | | | | | | | | | | |
| Osamu Date | 2005-04-22 | | | | | | | | | | | | |
| RECEIVING PARTY DATA | | | | | | | | | | | | | |
| <table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:20%;">Name</th> <th style="width:20%;">Street Address</th> <th style="width:20%;">Internal Address</th> <th style="width:15%;">City</th> <th style="width:15%;">State/Country</th> <th style="width:10%;">Postal Code</th> </tr> </thead> <tbody> <tr> <td>Sony Corporation</td> <td>7-35, Kitashinagawa 6-chome</td> <td></td> <td>Tokyo</td> <td>JP</td> <td>141-0001</td> </tr> </tbody> </table> | | Name | Street Address | Internal Address | City | State/Country | Postal Code | Sony Corporation | 7-35, Kitashinagawa 6-chome | | Tokyo | JP | 141-0001 |
| Name | Street Address | Internal Address | City | State/Country | Postal Code | | | | | | | | |
| Sony Corporation | 7-35, Kitashinagawa 6-chome | | Tokyo | JP | 141-0001 | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | |
| <table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:60%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number</td> <td>10531235</td> </tr> </tbody> </table> | | Property Type | Number | Application Number | 10531235 | | | | | | | | |
| Property Type | Number | | | | | | | | | | | | |
| Application Number | 10531235 | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | |
| <p>FAX NUMBER: (908) 654-0415</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.</p> <p>CUSTOMER NUMBER: 000530</p> | | | | | | | | | | | | | |
| NAME OF PERSON SIGNING: | Robert B. Cohen | | | | | | | | | | | | |
| DATE SIGNED: | 2005-11-02 | | | | | | | | | | | | |
| <p>Total Attachments: 2</p> <p>source=SONYJP419-usassn-A000001.tif</p> <p>source=SONYJP419-usassn-A000002.tif</p> | | | | | | | | | | | | | |

CH \$40.00 121095 10531235

Docket Number: SONYJP 3.3-403
Sony Reference No. S04P1161US00

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|---|---|
| <u>Osamu DATE</u> Name of Second Joint Inventor | Execution Date of U.S. Patent Application |
| <u>Saitama, Japan</u> Residence of Second Joint Inventor | April 22, 2005 |
| <i>Osamu Date</i> Signature of Second Joint Inventor | Date of this Assignment |

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

INFORMATION RECORDING APPARATUS AND INFORMATION RECORDING METHOD

for which an International Application was filed on July 13, 2004, PCT/JP2004/010269, designating the United States;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

| | |
|---|--|
| <u>Kenichiro ARIDOME</u> Name of First or Sole Inventor | _____ |
| <u>Kanagawa, Japan</u> Residence of First or Sole Inventor | _____ |
| <u>Kenichiro Aridome</u> Signature of First or Sole Inventor | <u>April 22, 2005</u> Date of this Assignment |